

Data sheet Product ICK BGA 27 x 27 x 14



Heatsinks and active heatsinks for processors>Heatsinks for BGAs
27 x 27 x 14 mm, for IC design BGA and others

Features

way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	27 mm
height:	14 mm
plate thickness:	2.5 mm
length:	27 mm
thermal resistance:	13.5 - 4 K/W
dissipation loss:	9.5 W
surface:	black anodised

Technical Drawing

